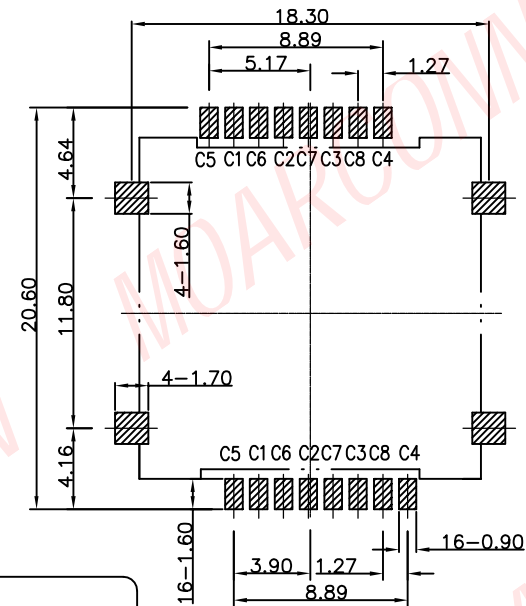
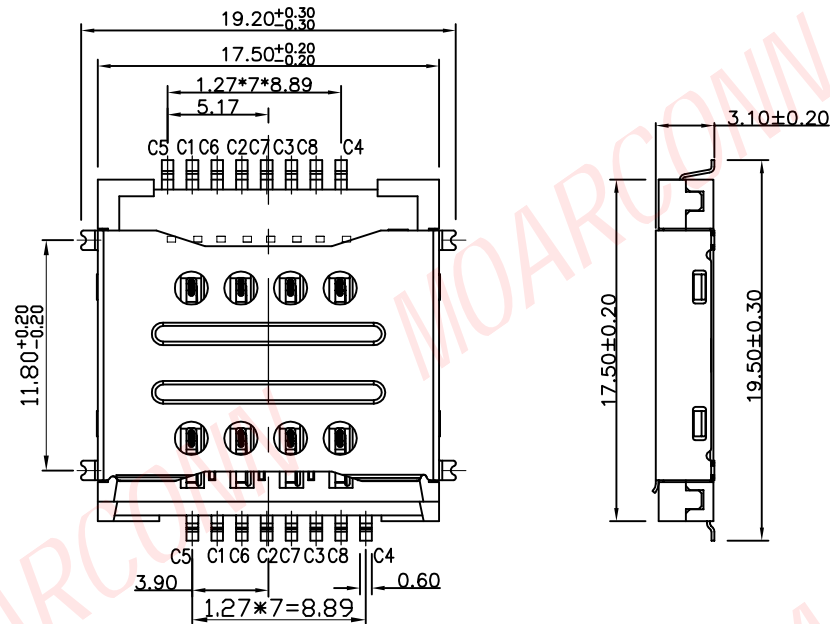
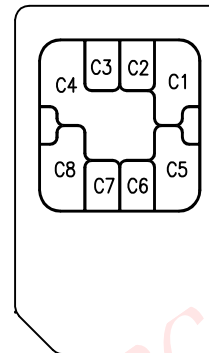


All materials, plating and process meet HF requirements.



RECOMMENDED PCB LAYOUT
(all tolerance are ±0.05)

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED



SIM CARD CIRCUIT

NOTE:

1.MATERIAL:

- A. HOUSING: LCP, UL 94-V0 COLOR: BLACK.
- B. CONTACT: PHOSPHOR BRONZE t=0.15.
- C. SHELL: SUS 210 t=0.15.

- 2. PLATING: Underplate: 30u' Nickel OVER ALL. Contact area: 1u' Gold.
Solder tails area: Tin Plated 80u' min.
SHELL Solder tails area: G/F Plated.

3.Electrical characteristics:

- A. Operating voltage: 250V(AC/DC).
- B. Current rating: 1AMP MAX.
- C. Operating temperature:-20°C~+85°C.
- D. Insulation resistance: 1000M ohme min. at 250VDC.
- E. Dielectric withstanding voltage: 500 VAC/1minute.
- F. Contact resistance:40m ohme max.

A	----	NEW RELEASE	FAJI	2022.06.14
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				

		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.25 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NAME : DUAL SIM CARD CONN. H3.1mm	DRAWING: Fa ji	DATE: 2022.06.14
		PRODUCT NO. : SM310-T1251-01-W	CHECK:	DATE:	
		DRAWING NO. : D-SM310-T1251-01-W	APPROVED:	DATE:	
			SCALE: 1:1	DWG ID: C D	
			REV.: A	PAGE: 1 OF 1	